

LNP™ THERMOTUF™ COMPOUND WF008N

DESCRIPTION

LNP™ THERMOTUF™ WF008N is a PBT based compound containing 40% glass for NMT application. Added features of this material include: high modulus, high metal bonding strength, and good chemical resistance.

TYPICAL PROPERTY VALUES

Revision 20191217

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, brk, Type I, 5 mm/min	133	MPa	ASTM D 638
Tensile Strain, brk, Type I, 5 mm/min	2.4	%	ASTM D 638
Tensile Modulus, 5 mm/min	11600	MPa	ASTM D 638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	205	MPa	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	11000	MPa	ASTM D 790
Tensile Stress, break, 5 mm/min	134	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.5	%	ISO 527
Tensile Modulus, 1 mm/min	11700	MPa	ISO 527
Flexural Stress, break, 2 mm/min	217	MPa	ISO 178
Flexural Modulus, 2 mm/min	11200	MPa	ISO 178
Bonding Strength ("T" treatment, shear type)	34	MPa	ISO 19095
IMPACT			
Izod Impact, unnotched, 23°C	960	J/m	ASTM D 4812
Izod Impact, notched, 23°C	145	J/m	ASTM D 256
Izod Impact, notched, -30°C	106	J/m	ASTM D 256
Izod Impact, unnotched 80*10*4 +23°C	59	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	14	kJ/m ²	ISO 180/1A
Izod Impact, notched 80*10*4 -30°C	11	kJ/m ²	ISO 180/1A
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	193	°C	ASTM D 648
HDT, 0.45 MPa, 3.2 mm, unannealed	217	°C	ASTM D 648
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	196	°C	ISO 75/Af
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	218	°C	ISO 75/Bf
CTE, -40°C to 40°C, flow	1.9E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	8.7E-05	1/°C	ASTM E 831
CTE, 23°C to 50°C, flow	1.7E-05	1/°C	ASTM E 831
CTE, 23°C to 50°C, xflow	9.0E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, flow	1.8E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	8.6E-05	1/°C	ISO 11359-2
CTE, 23°C to 50°C, flow	1.7E-05	1/°C	ISO 11359-2
CTE, 23°C to 50°C, xflow	8.9E-05	1/°C	ISO 11359-2
Relative Temp Index, Elec ⁽¹⁾	75	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽¹⁾	75	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽¹⁾	75	°C	UL 746B
PHYSICAL			

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Density	1.58	g/cm ³	ISO 1183
Melt Flow Rate, 250°C/5.0 kgf	10	g/10 min	ASTM D 1238
Melt Flow Rate, 275°C/5 kgf	22	g/10 min	ASTM D 1238
Melt Volume Rate, MVR at 250°C/5.0 kg	7	cm ³ /10 min	ISO 1133
Melt Volume Rate, MVR at 275°C/5 kg	15	cm ³ /10 min	ISO 1133
Mold Shrinkage, flow	0.25	%	SABIC method
Mold Shrinkage, xflow	0.65	%	SABIC method
ELECTRICAL			
Dielectric Constant, 1.1 GHz	3.78	-	SABIC method
Dielectric Constant, 1.9 GHz	3.76	-	SABIC method
Dielectric Constant, 5 GHz	3.73	-	SABIC method
Dielectric Constant, 10 GHz	3.80	-	SABIC method
Dissipation Factor, 1.1 GHz	0.0104	-	SABIC method
Dissipation Factor, 1.9 GHz	0.0096	-	SABIC method
Dissipation Factor, 5 GHz	0.0091	-	SABIC method
Dissipation Factor, 10 GHz	0.0082	-	SABIC method
FLAME CHARACTERISTICS ⁽¹⁾			
UL Yellow Card Link	E207780-104061413	-	-
UL Recognized, 94HB Flame Class Rating	≥0.7	mm	UL 94
INJECTION MOLDING			
Drying Temperature	100 – 120	°C	
Drying Time	2 – 4	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	250 – 270	°C	
Nozzle Temperature	255 – 275	°C	
Front - Zone 3 Temperature	250 – 270	°C	
Middle - Zone 2 Temperature	250 – 270	°C	
Rear - Zone 1 Temperature	240 – 260	°C	
Hopper Temperature	40 – 60	°C	
Mold Temperature	100 – 160	°C	

(1) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

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